

Triacs

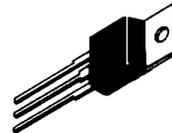
Silicon Bidirectional Thyristors

... designed for full-wave ac control applications primarily in industrial environments needing noise immunity.

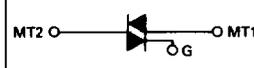
- **Guaranteed High Commutation Voltage**
dv/dt — 500 V/ μ s Min @ $T_C = 25^\circ\text{C}$
- High Blocking Voltage — V_{DRM} to 800 V
- Photo Glass Passivated Junction for Improved Power Cycling Capability and Reliability

MAC213 Series

TRIACS
12 AMPERES RMS
200 thru 800 VOLTS



CASE 221A-04
(TO-220AB)
STYLE 4



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MAXIMUM RATINGS ($T_J = 25^\circ\text{C}$ unless otherwise noted.)

Rating	Symbol	Value	Unit
Repetitive Peak Off-State Voltage, Note 1 ($T_J = -40$ to $+125^\circ\text{C}$, Gate Open) MAC213-4 MAC213-6 MAC213-8 MAC213-10	V_{DRM}	200 400 600 800	Volts
Peak Gate Voltage	V_{GM}	10	Volts
On-State Current RMS ($T_C = +85^\circ\text{C}$) Full Cycle Sine Wave 50 to 60 Hz	$I_T(\text{RMS})$	12	Amp
Peak Non-Repetitive Surge Current (One Full Cycle, 60 Hz, $T_C = +85^\circ\text{C}$) preceded and followed by Rated Current	I_{TSM}	100	Amp
Circuit Fusing Considerations ($T_C = +85^\circ\text{C}$, $t = 8.3$ ms)	I^2t	41	A^2s
Peak Gate Power ($T_C = +85^\circ\text{C}$, Pulse Width = 10 μs)	P_{GM}	20	Watts
Average Gate Power ($T_C = +85^\circ\text{C}$, $t = 8.3$ ms)	$P_{G(AV)}$	0.35	Watt
Peak Gate Current ($T_C = +85^\circ\text{C}$, Pulse Width = 10 μs)	I_{GM}	2.0	Amp
Operating Junction Temperature	T_J	-40 to +125	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	-40 to +150	$^\circ\text{C}$

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	$R_{\theta JC}$	2.1	$^\circ\text{C}/\text{W}$

Note 1. V_{DRM} for all types can be applied on a continuous basis. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

Devices listed in bold, italic are Motorola preferred devices.

MAC213 Series

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted.)

Characteristic	Symbol	Min	Typ	Max	Unit
Peak Blocking Current (Either Direction) (V _D = Rated V _{DRM} , Gate Open) T _J = 25°C T _J = +125°C	I _{DRM}	— —	— —	10 2.0	μA mA
Peak On-State Voltage (Either Direction) (I _{TM} = 17 A Peak; Pulse Width ≤ 2.0 ms, Duty Cycle ≤ 2.0%)	V _{TM}	—	1.3	1.75	Volts
Gate Trigger Current (Continuous dc) (Main Terminal Voltage = 12 Vdc, R _L = 100 Ohms) MT2(+), G(+) MT2(+), G(-) MT2(-), G(-)	I _{GT}	— — —	— — —	100 100 100	mA
Gate Trigger Voltage (Continuous dc) (Main Terminal Voltage = 12 Vdc, R _L = 100 Ohms) MT2(+), G(+) MT2(+), G(-) MT2(-), G(-) (Main Terminal Voltage = Rated V _{DRM} , R _L = 10 kΩ, T _J = +125°C) MT2(+), G(+); MT2(-), G(-); MT2(+), G(-)	V _{GT}	— — — 0.2	— — — —	2.0 2.0 2.0 —	Volts
Holding Current (Either Direction) (Main Terminal Voltage = 12 Vdc, Gate Open, Initiating Current = 200 mA)	I _H	—	—	100	mA
Turn-On Time (V _D = Rated V _{DRM} , I _{TM} = 17 A, I _{GT} = 120 mA, Rise Time = 0.1 μs, Pulse Width = 2.0 μs)	t _{gt}	—	1.5	—	μs
Critical Rate of Rise of Off-State Voltage (V _D = Rated V _{DRM} , Exponential Voltage Rise, Gate Open) T _J = 25°C T _J = +125°C	dv/dt(s)	500 200	— —	— —	V/μs

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TYPICAL CHARACTERISTICS

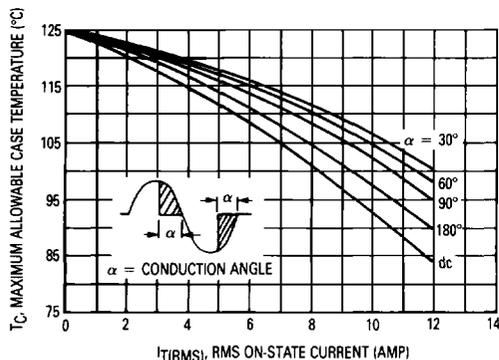


Figure 1. Current Derating

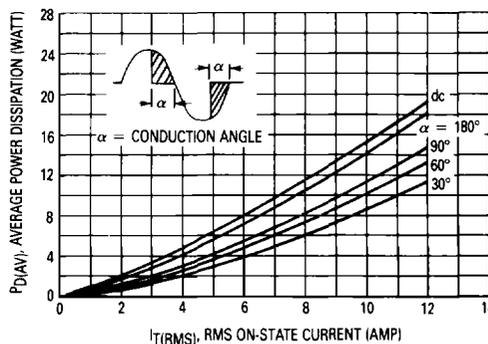


Figure 2. Power Dissipation

MAC213 Series

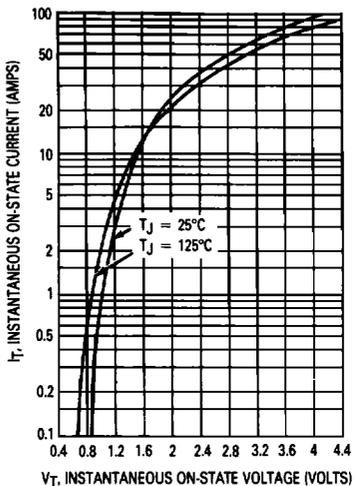


Figure 3. Maximum On-State Characteristics

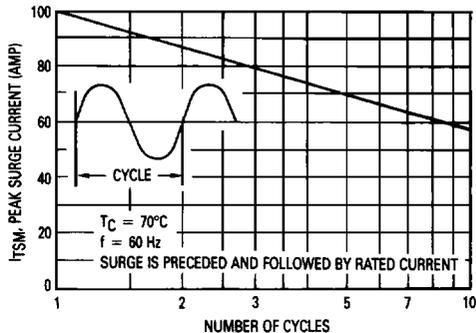


Figure 4. Maximum Non-Repetitive Surge Current

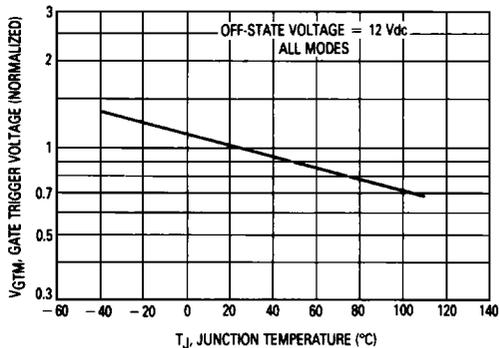


Figure 5. Typical Gate Trigger Voltage

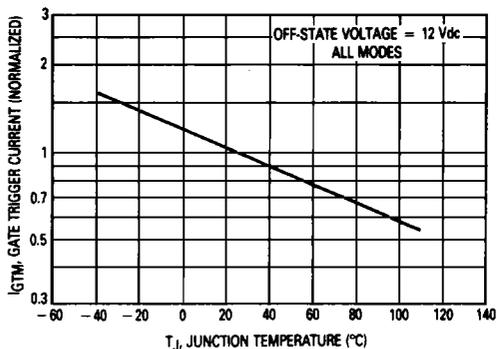


Figure 6. Typical Gate Trigger Current

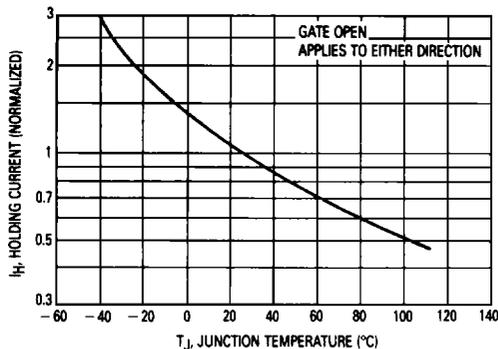


Figure 7. Typical Holding Current

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MAC213 Series

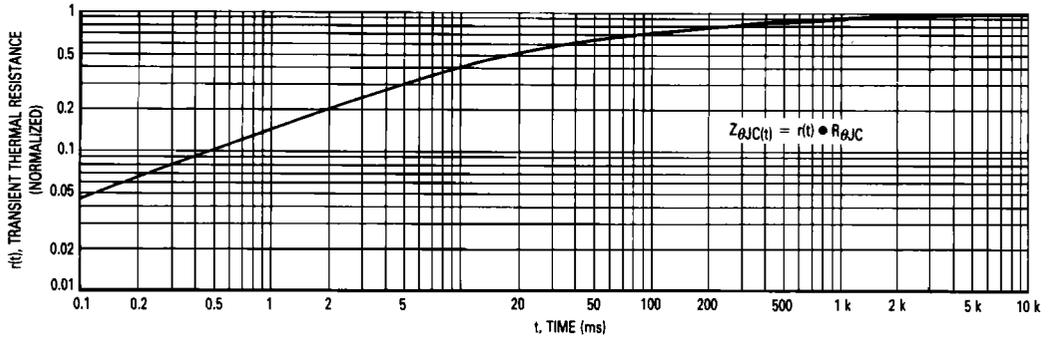


Figure 8. Thermal Response